Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.028”**

**C**

**.023”**

**.023”**

**.008”**

**A**

**.028”**

**FOR ZENER OPERATION:**

 **CATHODE MUST BE OPERATED POSITIVE WITH RESPECT TO ANODE.**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .008” min.**

**Backside: ISOLATED**

**APPROVED BY: DK DIE SIZE .038” X .038” DATE: 10/21/21**

**MFG: MICROSEMI / CDI THICKNESS .010” P/N: 1N937A**

**DG 10.1.2**

#### Rev B, 7/19/02